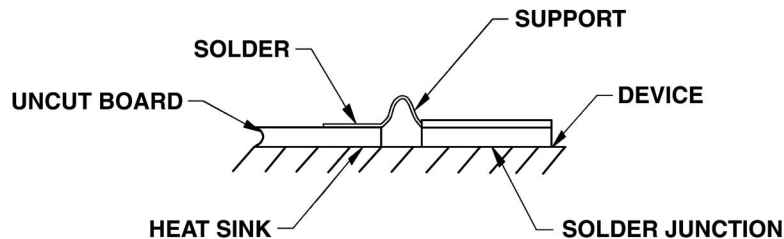


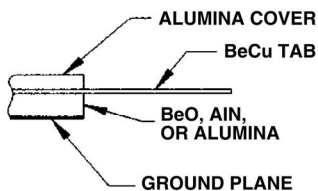
When mounting a flangeless device, it is important to obtain a solder joint between the device ground plane and the heat sink that is free of voids. Pretinning of the device ground plane and the heat sink is recommended. When soldering devices with palladium-silver terminals, a solder containing silver such as Sn62 should be used to help prevent leaching of the terminals. Devices with plated terminals can be soldered with standard Sn63 solder. Only eutectic solders should be used when mounting these devices. The tab contacts are treated the same way as the flanged device. Position the device on the pretinned heat sink and reflow the solder. Apply a downward force overcoming the surface tension of the solder and settle the device down to the heat sink surface. While maintaining the downward force, allow the solder to cool. The goal is to eliminate air voids and make the solder joint thin.

It is recommended that a small amount of mildly activated flux be used in any of the soldering operations. All flux residues should be removed with the appropriate solution after soldering.



Tab Options for Strain Relief

- PC Board Mount



- Strain Relief

